

ABS202 THRU ABS210

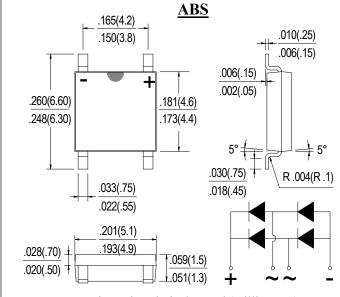
SINGLE PHASE 2.0 AMPS. GLASS PASSIVATED BRIDGE RECTIFIERS

FEATURE

- . Glass passivated junction.
- . Ideal for printed circuit board.
- . Reliable low cost construction utilizing molded plastic technique.
- . High surge current capability.
- . High temperature soldering guaranteed: 260°C/10 seconds at terminals.
- . UL Recognized File # E338195.

MECHANICAL DATA

- . Case Material: "Green" Molding compound, UL flammability classification rating 94V-0, "Free halogen"
- . Moisture sensitivity level:level 2a,per J-STD-020
- . Polarity:Polarity as marked on the body
- . Weight: 0.10g (approximately)



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at $25\,^\circ\!\!\!\!\mathrm{C}$ ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Tor capacitive load, derate current by 2070	I	T	I	I	T	I	T
Type Number	SYM BOL	ABS202	ABS204	ABS206	ABS208	ABS210	units
Maximum Recurrent Peak Reverse Voltage	$V_{ m RRM}$	200	400	600	800	1000	V
Maximum RMS Voltage	$V_{ m RMS}$	140	280	420	560	700	V
Maximum DC blocking Voltage	$V_{ m DC}$	200	400	600	800	1000	V
Maximum Average Forward rectified Current @ T_A =40°C	I _{F(AV)}	2.0					A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rate load (JEDEC method)	$I_{ m FSM}$	50					A
	$V_{ m F}$	1.1 0.95					V
Maximum DC Reverse Current $@T_J = 25^{\circ}\text{C}$ at rated DC blocking voltage $@T_J = 125^{\circ}\text{C}$	$I_{ m R}$	5.0 100.0					μΑ
I ² t Rating for Fusing (t < 8.3ms)	I ² t	12.5					A ² Sec
Typical Junction Capacitance Per Leg (Note1)	C _J	17					pF
Typical Thermal Resistance (Note2)	$R_{ m JC} \ R_{ m JA}$	18 50					°C /W
Storage Temperature	T _{STG}	-55 to +150					°C
Operating Junction Temperature	$T_{ m J}$	-55 to +150					°C

Note:

- 1. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
- 2. Thermal resistance junction to case, lead and ambient in accordance with JESD-51.

Unit mounted on glass-epoxy substrate with 1oz/ft2_20x20 mm copper pad per pin with heatsink

RATING AND CHARACTERISTIC CURVES (ABS202 THRU ABS210)

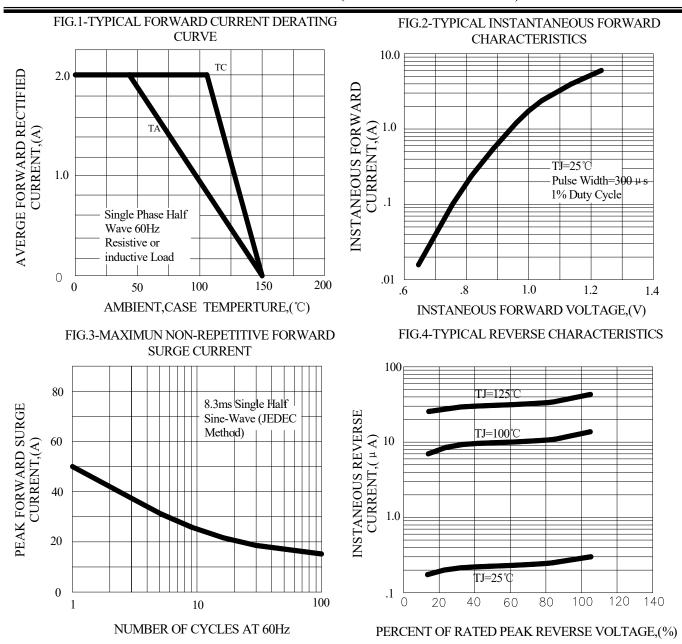


FIG.5-TYPIAL JUNCTION CAPAOTANCE

